

ESDHP3Z5.0C

List

List.....	1
Package outline.....	2
Features.....	2
Applications.....	2
Mechanical data.....	2
Maximum ratings	2
Electrical characteristics.....	2
Rating and characteristic curves.....	3
Pinning information.....	4
Marking.....	4
Suggested solder pad layout.....	4
Package Information.....	5
Reel packing.....	6
Suggested thermal profiles for soldering processes.....	6

ESDHP3Z5.0C

Bi-Directional TVS For ESD Protection : 5.0V

Features

- Protects one power line or data line.
- Operating voltage: 5V.
- Complies with following standards:
 - IEC 61000-4-2 (ESD) ± 30 kV (Air).
 - IEC 61000-4-2 (ESD) ± 30 kV (Contact).
 - IEC 61000-4-5 (Lightning) 120A (8/20 μ s).
- Lead-free parts meet RoHS requirements.
- Suffix "-H" indicates Halogen-free part, ex.ESDHP3Z5.0C-H.

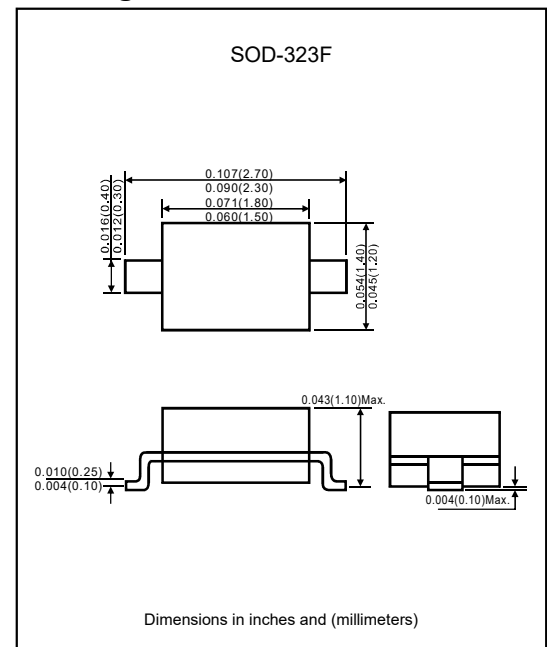
Applications

- Mobile Phones and Accessories.
- Battery protection.
- USB VBUS.
- Power line protection.
- Hand held portable applications.

Mechanical data

- Epoxy:UL94-V0 rated flame retardant.
- Case : Molded plastic, SOD-323F.
- Terminals : Solder plated, solderable per MIL-STD-750, Method 2026.
- Mounting Position : Any.

Package outline



Maximum ratings (At $T_A=25^\circ\text{C}$ unless otherwise noted)

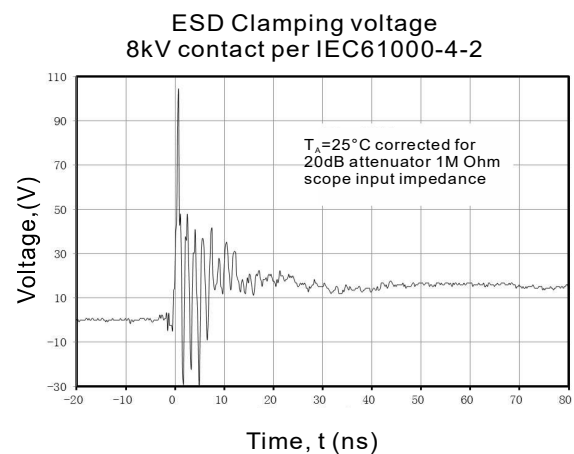
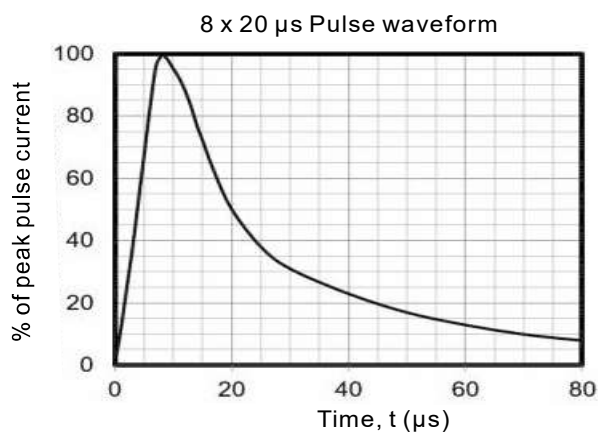
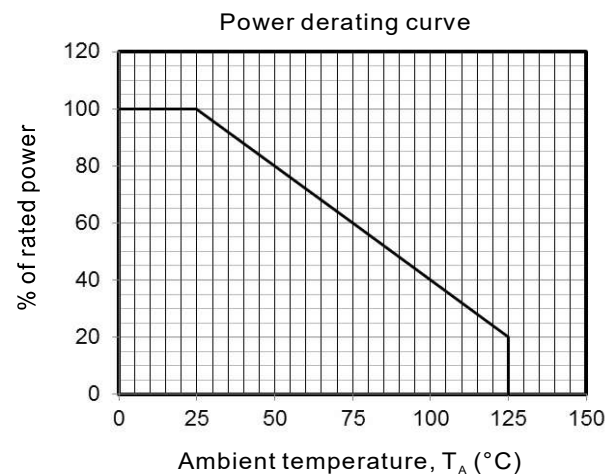
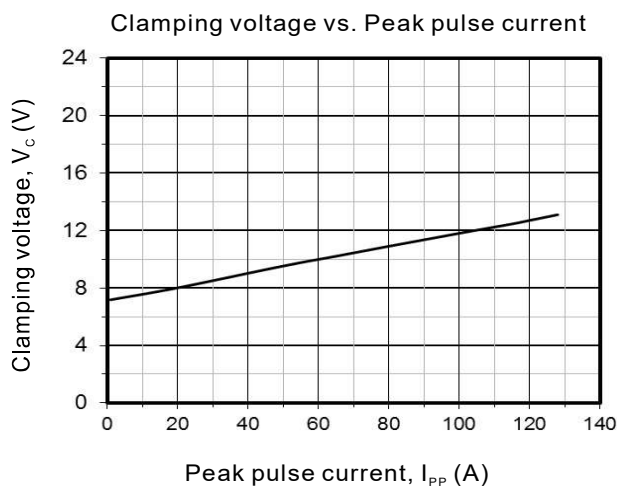
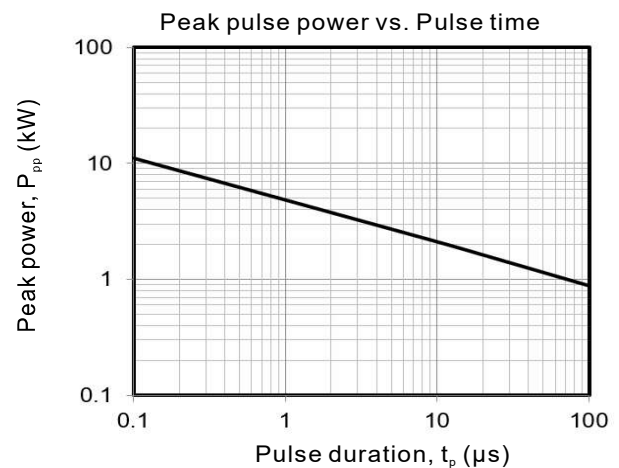
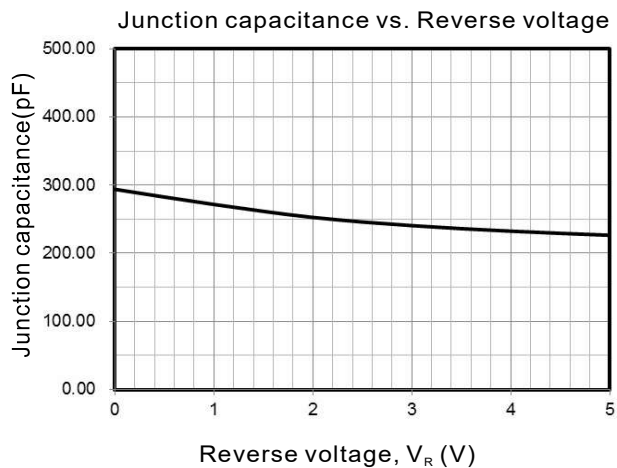
Parameter	Symbol	Value	Unit
Peak pulse power (8/20 μ s)	P_{PK}	1620	W
Peak Pulse Current (8/20 μ s)	I_{PP}	120	A
ESD Per IEC 61000-4-2 (Air)	V_{ESD}	± 30	KV
ESD Per IEC 61000-4-2 (Contact)		± 30	
Operating temperature	T_J	+125	$^\circ\text{C}$
Storage temperature range	T_{STG}	-55 to +150	$^\circ\text{C}$

Electrical characteristics (At $T_A=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Reverse working voltage	V_{RWM}				5	V
Breakdown voltage	V_{BR}	$I_T = 1\text{mA}$	5.6		8	V
Reverse leakage current	I_R	$V_{RWM} = 5\text{V}$			0.5	μA
Clamping voltage	V_C	$I_{PP} = 20\text{A}$ (8/20 μ s pulse)			8.5	V
		$I_{PP} = 120\text{A}$ (8/20 μ s pulse)			13.5	
Junction capacitance	C_J	$V_R = 0\text{V}$, $f = 1.0\text{MHz}$		300		pF

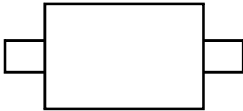
ESDHP3Z5.0C

Rating and characteristic curves



ESDHP3Z5.0C

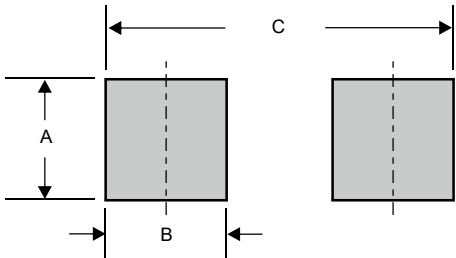
Pinning information

Pin	Simplified outline	Symbol
Bi-directional		

Marking

Type number	Marking code
ESDHP3Z5.0C	58D

Suggested solder pad layout

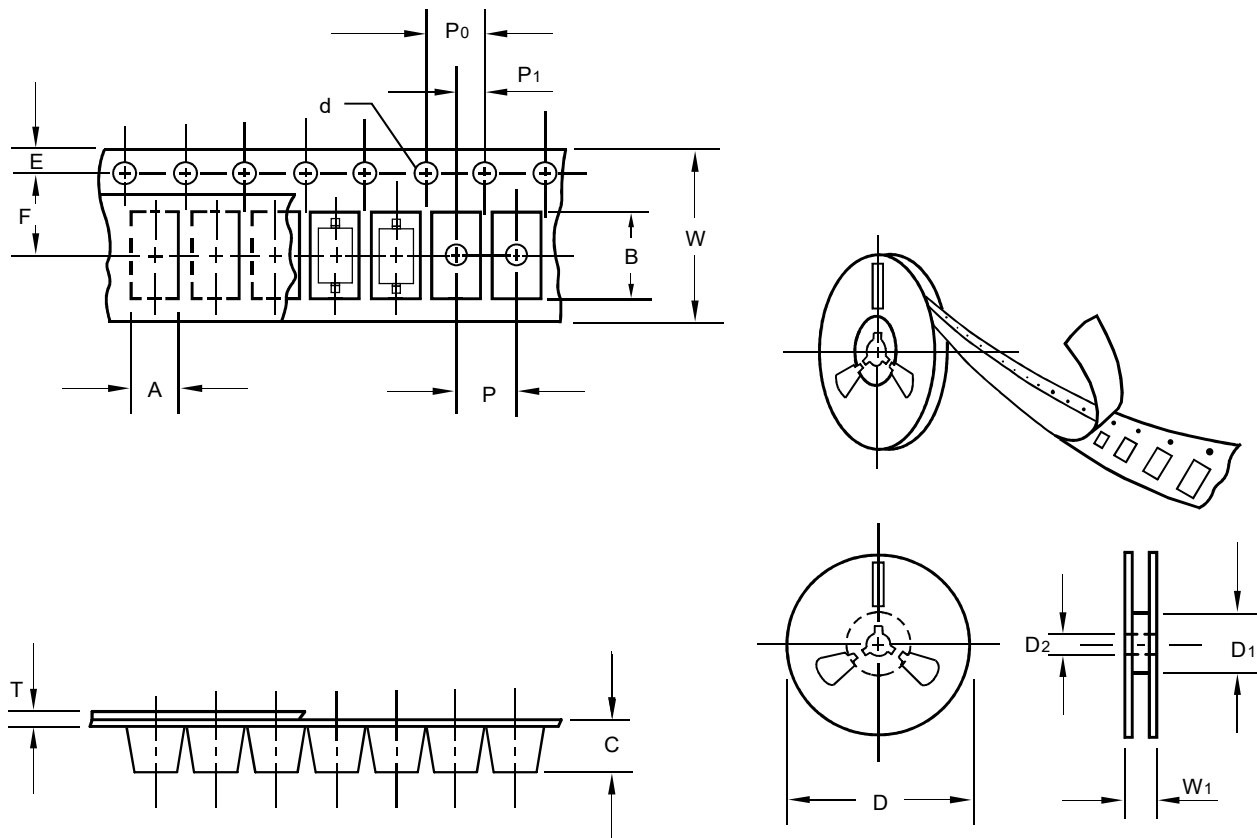


Dimensions in inches and (millimeters)

PACKAGE	A	B	C
SOD-323F	0.031 (0.80)	0.031 (0.80)	0.120 (3.15)

ESDHP3Z5.0C

Packing information



unit:mm

Item	Symbol	Tolerance	SOD-323F
Carrier width	A	0.1	1.48
Carrier length	B	0.1	3.30
Carrier depth	C	0.1	1.25
Sprocket hole	d	0.1	1.50
13" Reel outside diameter	D	2.0	-
13" Reel inner diameter	D ₁	min	-
7" Reel outside diameter	D	2.0	178.00
7" Reel inner diameter	D ₁	min	55.00
Feed hole diameter	D ₂	0.5	13.00
Sprocket hole position	E	0.1	1.75
Punch hole position	F	0.1	3.50
Punch hole pitch	P	0.1	4.00
Sprocket hole pitch	P ₀	0.1	4.00
Embossment center	P ₁	0.1	2.00
Overall tape thickness	T	0.1	0.23
Tape width	W	0.3	8.00
Reel width	W ₁	1.0	9.50

Note: Devices are packed in accordance with EIA standard RS-481-A and specifications listed above.

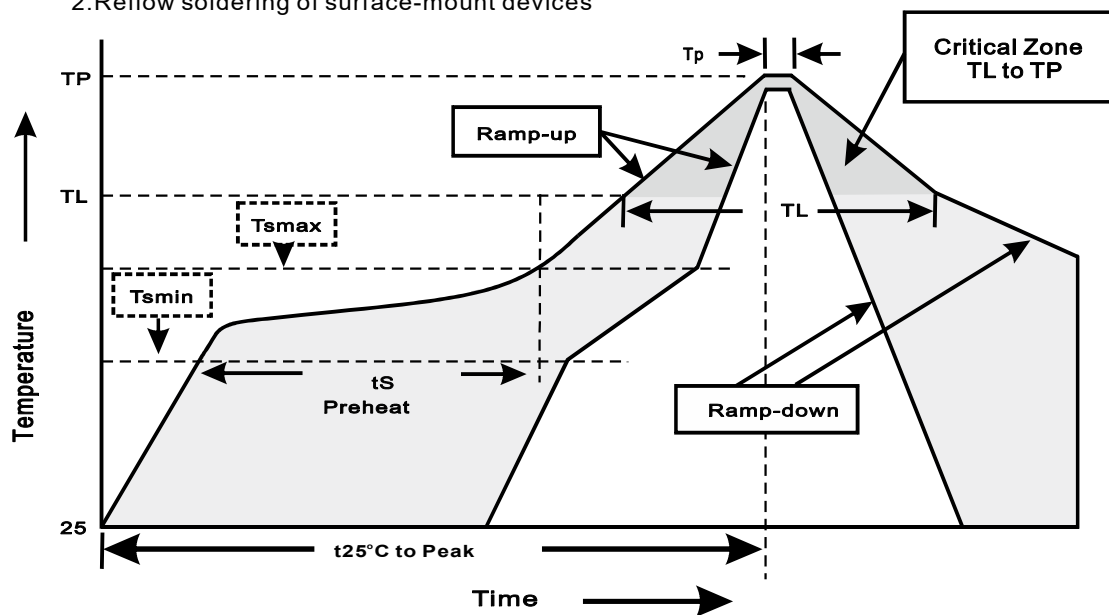
ESDHP3Z5.0C

Reel packing

PACKAGE	REEL SIZE	REEL (pcs)	COMPONENT SPACING (m/m)	BOX (pcs)	INNER BOX (m/m)	REEL DIA, (m/m)	CARTON SIZE (m/m)	CARTON (pcs)
SOD-323F	7"	3,000	4.0	30,000	183*123*183	178	382*257*387	240,000

Suggested thermal profiles for soldering processes

- 1.Storage environment: Temperature=5°C~40°C Humidity=55%±25%
- 2.Reflow soldering of surface-mount devices



3.Reflow soldering

Profile Feature	Soldering Condition
Average ramp-up rate(T _L to T _P)	<3°C/sec
Preheat -Temperature Min(T _{Smin}) -Temperature Max(T _{Smax}) -Time(min to max)(t _S)	150°C 200°C 60~120sec
T _{Smax} to T _L -Ramp-upRate	<3°C/sec
Time maintained above: -Temperature(T _L) -Time(t _L)	217°C 60~260sec
Peak Temperature(T _P)	255°C-0/+5°C
Time within 5°C of actual Peak Temperature(t _P)	10~30sec
Ramp-down Rate	<6°C/sec
Time 25°C to Peak Temperature	<6minutes